X3-25M

Innovative Integration
a molex company

PCI Express XMC Module with Two 105 MSPS A/Ds, Two 50 MSPS DACs and 1.8M Spartan 3A DSP FPGA
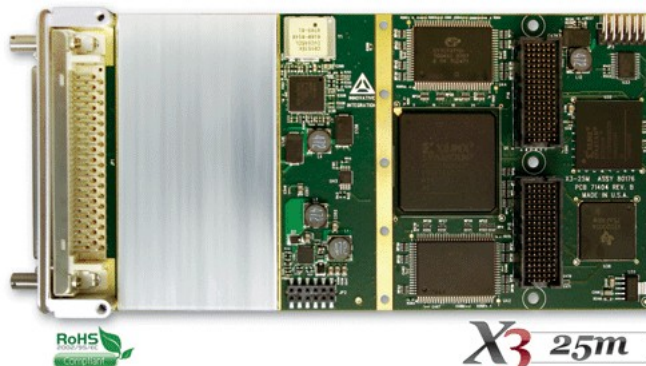
FEATURES

- Two 105 MSPS, 16-bit A/D channels
- -110 dB noise floor, 97 dB SFDR A/Ds
- Two 50 MSPS, 16-bit DAC channels
- +/-2V, +/-1V, +/-0.2V input ranges
- +/-2V output range
- 16-bits front panel DIO (8 differential pairs)
- Xilinx Spartan3A DSP, 1.8M gate FPGA
- 4MB SRAM
- Programmable or external sample clock
- Synchronized system sampling using common reference clock and triggers
- Framed, software or external triggering
- Log acquisition timing and events
- 44 bits digital IO on P16
- Power management features
- PCI Express XMC Module (75x150 mm)
- Use in any PCI Express desktop, compact CPI/PXI, or cabled PCI Express application

APPLICATIONS

- Stimulus-response measurements
- High speed servo controls
- Arbitrary Waveform Generation

SOFTWARE

- Data Acquisition, Logging and Analysis applications provided
- Windows/Linux Drivers
- C++ Host Tools
- VHDL/MATLAB Logic Tools

MATLAB®

XILINX®

DESCRIPTION

The X3-25M is an XMC IO module featuring two 16-bit, 105 MSPS A/D channels and two 16-bit, 50 MSPS DAC channels designed for high speed stimulus-response, ultrasound, and servo control applications.

Flexible trigger methods include counted frames, software triggering and external triggering. The sample rate clock is either an external clock or on-board programmable PLL clock source.

Data acquisition control, signal processing, buffering, and system interface functions are implemented in a Xilinx Spartan3A DSP 1.8M gate FPGA device. Two 512Kx32 memories provide data buffering and FPGA computing memory.

The logic can be fully customized using VHDL and MATLAB using the FrameWork Logic toolset. The MATLAB BSP supports real-time hardware-in-the-loop development using the graphical, block diagram Simulink environment with Xilinx System Generator.

The PCI Express interface supports continuous data rates up to 180 MB/ s between the module and the host. A flexible data packet system implemented over the PCIe interface provides both high data rates to the host that is readily expandable for custom applications.

Innovative Integration • phone 805 383-3994 • fax 805 482-8470 • www.innovative-dsp.com

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This electronics assembly can be damaged by ESD. Innovative Integration recommends that all electronic assemblies and components circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION

Product	Part Number	Description
X3-25M	80176-0	XMC module with two 105 MSPS A/D , two 50 MSPS DACs, 1.8M gate FPGA, 4MB SRAM
Logic		
X3-25M FrameWork Logic	55020	X3-25M FrameWork Logic board support package for RTL and MATLAB. Includes technical support for one year.
Software		
Linux	54042	Linux for SBC-Linux-ComEx, eInstrument-PC
Windows XP	54043	Windows XP Embedded for SBC-ComEx, eInstrument-PC
Windows XP	54044	Windows XP Pro for SBC-ComEx
Windows Vista	54046	Windows Vista Business for SBC-ComEx
Windows 7	54050	Windows 7 Pro 32-bit
Windows 7	54051	Windows 7 Embedded
Windows 7	54052	Windows 7 Pro 64-bit
Windows 7	54054	Windows 7 Pro 64-bit Embedded
Power		
Power Supply	80200-0	SBC-ComEx, eInstrument-PC Power Supply, DC (8-24V) input, 125W
Power Supply	80200-1	SBC-ComEx, eInstrument-PC Power Supply, AC (110-240) input, 125W, USA/Japan/Korea/Taiwan power cord
Power Supply	80200-2	SBC-ComEx, eInstrument-PC Power Supply, AC (110-240) input, 125W, UK/Australia/India power cord
Power Supply	80200-3	SBC-ComEx, eInstrument-PC Power Supply, AC (110-240) input, 125W, EU power cord
Cables		
MDR68 cable	65057	IO cable with MDR68 plug on each end, 3 feet length (0.92m)
MMCX to SMA cable	67048G	MMCX to SMA cable

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Coax cable assembly for X3-25M	67061	Cable assembly provides coax cables with BNC termination for A/D, DAC, trigger in clock inputs. Front panel DIO provided on ribbon cable terminated by 16 pin IDC.
Breakout Cable	67060	MDR68 to coax cables with BNC terminations, 1 meter length.
Breakout	80112-1	MDR68-female to screw terminal block
Breakout	80116-0	MDR 68 BREAKOUT CABLE
MDR Cable	80116-1	MDR cable 68-pin and screw terminal block
Adapters		
XMC-PCIe x1 Adapter	80172-0	PCI Express Carrier card for XMC PCI Express modules, x1 lanes
PCIe X1 Cable Adapter	80181-0	Desktop PCI Express X1 Cable Adapter
PCIe X1 Cable Adapter	80186-0	Laptop PCI Express X1 Cable Adapter
XMC to CompactPCI Adapter	80207-0	CompactPCI to XMCe Adapter Board
cPCI-XMCe Adapter	80207-1-L4	cPCI-XMCe Adapter 3U Conduction Cooled
CPEX4	80246-0	X4 PCI Express Cable adapter card
XMC Adapter for 3U OpenVPX	80260-3	VPX-XMC 3U ADAPTER, conduction cooled, without REDI covers for X3 modules
XMC Adapter for 3U OpenVPX	80260-3RC	VPX-XMC 3U ADAPTER, conduction cooled, with REDI covers for X3 modules
XMC Adapter for 3U OpenVPX	80260-3RCA	VPX-XMC 3U ADAPTER, conduction cooled, with REDI covers for X3 modules & assembly
XMC-PCI Adapter	80167	PCI Carrier card for XMC PCI Express modules, 64-bit PCI-X
XMC-cPCI Adapter	80207	3U Compact PCI/PXI Carrier card for XMC PCI Express modules, 64-bit PCI-X
XMC-Cabled PCIe Adapter	90181	Cabled PCI Express Carrier card for XMC PCI Express modules, single-lane.
eInstrument-DAQ Node	90181-0	XMC module carrier with 2.5 Gbps cabled PCI Express link to Host Computer housed in a rugged aluminum enclosure.
CPEX4 Hub	90241-0	Cabled PCI Express 4-port Hub including chassis
Framework		
Logic	55020	Framework Logic support for X3-25M module
XMC Modules		
X3-Timing	80234-0	MDR cable 68-pin and screw terminal block

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X3-Timing	80234-1	XMC Module, 1 ppm crystal, no GPS
X3-Timing	80234-2	PCI Express XMC Module, 500 ppb crystal, with GPS
X3-Timing	80234-3	XMC Module, 1 ppm crystal, w/GPS
Embedded PC Host		
eInstrument PC	90199	Embedded PC XMC host with support for two XMC modules for standalone applications.
Custom Engineering and Consulting Services		
Engineering Services	56004	Software/hardware/firmware development
Technician Services	56005	Mechanical fabrication - Electronics prototyping
Premium Services	56006	Rapid turnaround premium, Engineering or Technician Services (add to base rate)
Visit	56009	Engineer Visit On Site for installation, application assistance, in-house training, custom SW
IP Blocks		
IP-TINY DDS	58003-0	1/3 size of Xilinx DDS with equal SFDR. Net version
IP-TINY DDS	58003-1	1/3 size of Xilinx DDS with equal SFDR, source version
IP-XLFFT	58011-0	Core for 64K to 1M points FFT for 1-D, 2-D signal Netlist undle with hardware
IP-XLFFT	58011-1	Core for 64K to 1M points FFT for 1-D, 2-D signal Netlist
IP-WINDOWING	58012-0	Run-time configurable Hann, Blackman, and Boxcar data windowing functions Netlist bundle with hardware
IP-WINDOWING	58012-1	Run-time configurable Hann, Blackman, and Boxcar data windowing functions Netlist
IP-WINDOWING	58525-0	Netlist version
IP-WINDOWING	58525-1	Source version
VPX		
VPX-COMEX	80271-0	3U VPX CPU Card, Spartan6 Forced Air Cooling, no REDI covers
VPX-COMEX	80271-0-L1	3U VPX CPU Card, Spartan6 Conduction Cooling, no REDI covers
VPX-COMEX	80271-0-L2	3U VPX CPU Card, Spartan6 Conduction Cooling, no REDI covers
VPX-COMEX	80271-0-L3	3U VPX CPU Card, Spartan6 Conduction Cooling, no REDI covers
VPX-COMEX	80271-0R-L0	Intel I7 @ 2.53 GHz, 128GB SSD Card with REDI covers
VPX-COMEX	80271-0R-L1	Intel I7 @ 2.53 GHz, 128GB SSD Card with REDI covers
VPX-COMEX	80271-0R-L3	Intel I7 @ 2.53 GHz, 128GB SSD Card with REDI covers
RTM-ComEx	80276-0	Rear terminal module for VPX-ComEx
RTM-ComEx	80276-0-L1	Rear terminal module for VPX-ComEx

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RTM-ComEx	80276-0-L3	Rear terminal module for VPX-ComEx
VPXI-Extension	90277-0	VPXI-Extension
Media		
DVD	57001	Innovative Integration Installation DVD
Recorders		
Andale Turnkey Logging System	90036-1	2.4 TB RAID0 Array, 700 MB/s
Andale Turnkey Logging System	90036-11	Sustained rates limited to 1600 MB/s
Andale Turnkey Logging System	90036-12	14.4 TB RAID0 Array, 1600 MB/s
Andale Turnkey Logging System	90036-13	9.6 TB RAID0 Array, 1200 MB/s
Andale Turnkey Logging System	90036-14	48 TB RAID0 Array, 2400 MB/s
Andale Turnkey Logging System	90036-2	Sustained rates limited to 300 MB/s
Andale Turnkey Logging System	90036-4	4.8 TB RAID0 Array, 850 MB/s
Andale Turnkey Logging System	90036-5	Sustained rates limited to 850 MB/s
Andale Turnkey Logging System	90036-6	Sustained rates limited to 1000 MB/s
Andale Turnkey Logging System	90036-7	Sustained rates limited to 500 MB/s
Andale Turnkey Logging System	90036-8	14.4 TB RAID0 Array, 2400 MB/s
Andale Turnkey Logging System	90036-9	Sustained rates limited to 1600 MB/s
Systems		
Mezzanine Card	80208-1	Mezzanine card for SBC-ComEx
Mezzanine Card	80242-0	Mezzanine card for eInstrumentPC and SBC-ComEx exposing J16 signals from XMC sites 0 and 1, plus SBC-ComEx baseboard digital I/O signals, 1 ppb stability clock with GPS
Precision GPS Option	80247-0	Precision GPS Option for eInstrument PC and Atom. Includes Trimble Mini-T GPS receiver, Bullet III antenna and 10 M cable
eInstrument-PC	90199-1	Rackmount Adapter Kit

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Low-Power eInstrument-PC	90200-0	90190-0+AC supply+chassis+boot SSD
Performance eInstrument-PC	90200-1	90190-1+AC supply+chassis+boot SSD
Performance ePC	90200-1A	90190-1+AC supply+chassis+boot SSD+VCO 350-460 MHz
Extreme eInstrument-PC	90200-2	90190-2+AC supply+chassis+boot SSD
Extreme eInstrument-PC	90200-3	90190-4+AC supply+chassis, 10-280 MHz SI570 VCO
Extreme eInstrument-PC	90200-5	90190-4+AC supply+chassis, 10-945 MHz SI570 VCO
Extreme eInstrument-PC	90200-6	Extreme eInstrument PC with SBC-ComEx carrier, DC supply, (10-945 MHz SI570 VCO range) I7 dual core at 2.5 Ghz, 4GB RAM and Enclosure for SBC-ComEx and SBC COMEX Power Supply, AC (110-240) input, 125W, USA/Japan/Korea/Taiwan power cord.
Low Power eInstrument ATOM PC	90201-0	90191-0+AC supply+chassis+Flash boot
Extreme eInstrument ATOM PC	90201-1	90191-2+AC supply+chassis+Flash boot
Low Power eInstrument ATOM PC	90201-3	Low-power eInstrument-PC ATOM PC with SBC-ComEx carrier, DC supply, ATOM CPU, 1GB RAM and Enclosure for SBC-ComEx and SBC COMEX Power Supply, DC (12V) input, 125W.
Extreme eInstrument ATOM PC	90201-4	90191-2+AC supply+chassis
Extreme eInstrument ATOM PC	90201-5	Extreme eInstrument ATOM PC with SBC-ComEx carrier, DC supply I7 dual core, 4GB RAM and enclosure for SBC-ComEx plus SBC COMEX power supply, DC (12V) input, 125W.
VPXI-ePC	90271-0	VPXI-ePC
VPXI-ePC	90271-0	VPXI-ePC conduction cooled cooled 3U 1/2 rack OpenVPX 5 expansion slots Rugged Level 1
VPXI-ePC	90271-0	VPXI-ePC conduction cooled cooled 3U 1/2 rack OpenVPX 5 expansion slots Rugged Level 2
VPXI-ePC	90271-0	VPXI-ePC conduction cooled cooled 3U 1/2 rack OpenVPX 5 expansion slots Rugged Level 3
Storage		
Hitachi HTS722020K9A300	306019	200GB 7200 RPM SATA 3.0Gb/s Hard Drive
Disk Drive	36028	Solid state disk drive for SBC ComEx - 160 GB

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Flash Drive	49016	4 Gigabytes memory USB Embedded
Western Digital Scorpio WD800BEVS	49017-0	80GB 5400 RPM SATA 1.5Gb/s Hard Drive
Flash Drive	49018	16 Gigabytes memory USB Embedded
Hard Disk	80212-0	Hard Disk Drive for SBC COMEX, eInstrument-PC; 200 GB
Hard Disk	80212-1	High Performance Hard Disk Drives for SBC COMEX, eInstrument-PC; two drives, 200 GB each
VelociRaptor WD6000HLHX	80212-3	600GB 10000 RPM 32MB Cache 2.5" Hard Drive
Disk Drive	80263	INTEL SOLID STATE DRIVE V SERIES SNV125-S2BD/30GB 2.5"
GPS		
Tyco A1029-D GPS antenna	68013G	Active, +25dB, 3.3V, SMA cable
GPS RECEIVER MODULE	68015G	Trimble Mini-T, high accuracy, 10 MHz output
GPS Antenna	68016G	Trimble Bullet III, 5V
NavSync CW25	80261	GPS Module for SBC-ComEx
GPS receiver and active antenna	90196-0	GPS receiver and active antenna (P/Ns 68013G + 80261)
GPS receiver and active antenna	90198-0	Trimble Mini-T GPS receiver and active antenna (P/Ns 68015G + 68013G)

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X3-25M Block Diagram
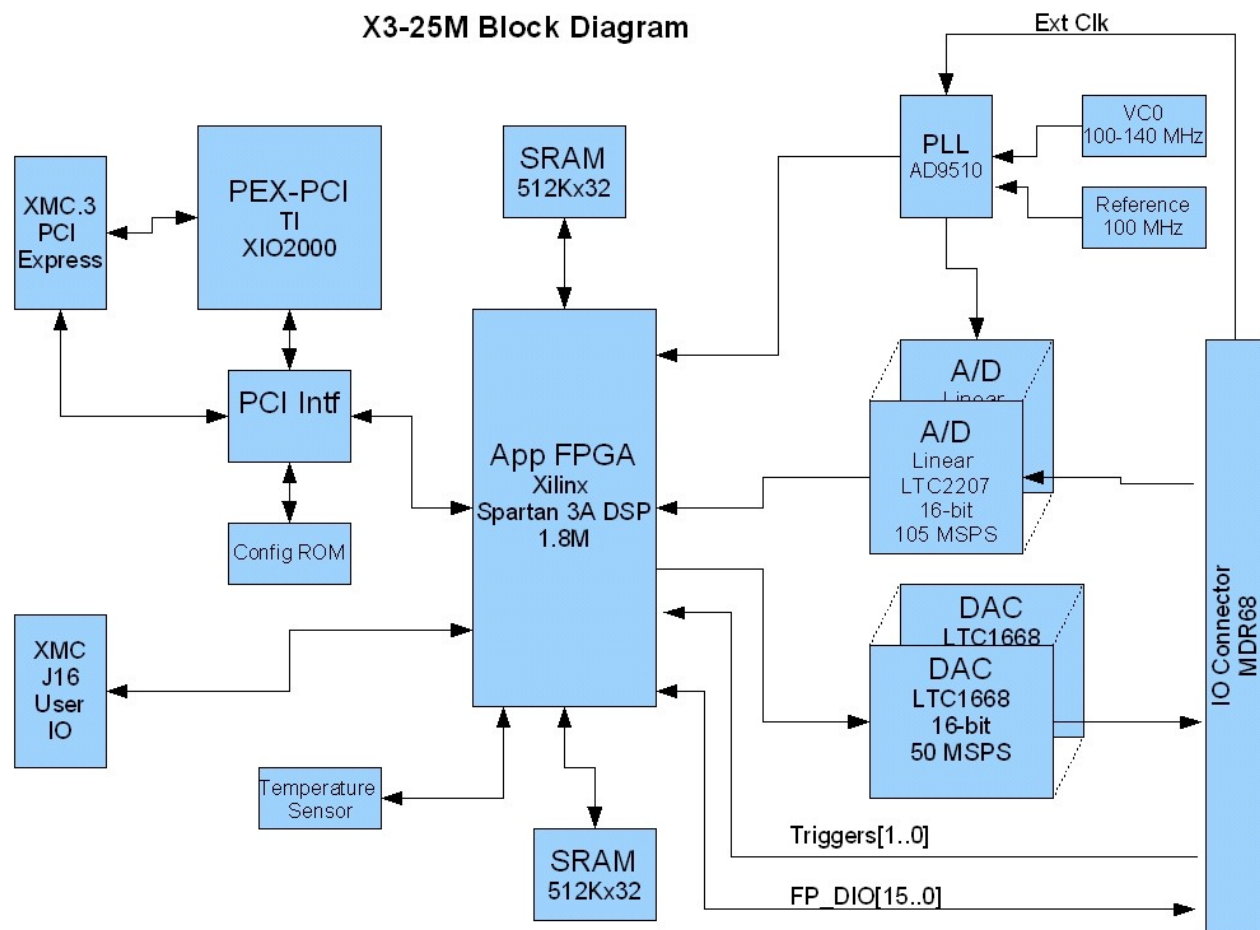
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Standard Features

Analog	
Inputs	2
Input Ranges	Programmable: +/-2V, +/-1V and +/-0.2V
Input Type	Single ended, DC coupled
Input Impedance	50 ohm
A/D Device	Linear Technology LTC2207
A/D Resolution	16-bit
A/D Sample Rate	1 MHz to 105 MHz ** Decimation feature in logic used for lower data rates
Outputs	2
Output Range	+/-2V
Output Type	Single ended, DC coupled
Output Impedance	50 ohm
DAC Device	Linear Technology LTC1668
DAC Resolution	16-bit
DAC Sample Rate	DC to 50 MHz
Data Format	2's complement, 16-bit integer
Connector	MDR68
Calibration	Factory calibrated. Gain and offset errors are digitally corrected in the FPGA. Non-volatile EEPROM coefficient memory.

Front Panel Digital IO	
Total Number of Bits	16
Balanced Pairs	6
Signal Standard	LVTTL May be configured as LVDS 2.5
Drive	+/-12 mA (LVTTL)
Connector	MDR68

FPGA	
Size	1.8M gate equivalent
Flip-Flops	33,280
Multipliers	84
CLB	4160
Block RAMs	84 (1512K bits)
FPGA Device	Xilinx Spartan3A DSP XC3SD1800A-4FGG676C
Configuration	SelectMAP from PCIe interface JTAG during development
Clock Rate	107 MHz system clock

Memory	
Size	4 MB total 2 devices @ 512Kx32 each
Type	Synchronous ZBT SRAM
SRAMs	Cypress CY7C1371D-133AXC
Uses	FPGA Buffer Memory FPGA computation memory
Clock Rate	107 MHz

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Host Interface	
Type	PCI Express; single lane
Sustained Data Rate	180 MB/s
Protocol	Packet data
Connector	XMC P15
Interface Standard	PCIe 1.0a; VITA 42.3
Logic Update	In-system reconfiguration

P16 Digital IO	
Total Number of Bits	44
Balanced Pairs	24
Signal Standard	LVTTL Configurable as LVDS 2.5V
Drive	+/-12 mA (LVTTL)
Connector	XMC P16

Clocks and Triggering	
Clock Sources	PLL or External
PLL Output	4 MHz to 140 MHz
PLL Resolution	1530 Hz
PLL Jitter	<1 ps RMS
PLL Programming	Host programmed via PCIe
PLL Reference	Internal: 100 MHz clock External reference : J16 input
Triggering	External, software, acquire N frame
Decimation	1:1 to 1:4095 in FPGA
Channel Clocking	All channels are synchronous
Multi-card Synchronization	External triggering, clock, and PLL reference are supported.

Power Management	
Temperature Monitor	May be read by the host software
Alarms	Software programmable warning and failure levels
Over-temp Monitor	Disables analog IO power supplies
Power Control	Channel enables and power up enables
Heat Sinking	Conduction cooling supported. (subset of VITA20)

Physicals	
Form Factor	Single width IEEE 1386 Mezzanine Card
Size	75 x 150 mm
Weight	100g
Hazardous Materials	Lead-free and RoHS compliant

Acquisition Monitoring	
Alerts	Trigger, Queue Overflow, Channel Over-range, Timestamp Rollover, Temperature Warning, Temperature Failure, PLL Unlocked
Alert Timestamping	9.3 ns resolution, 32-bit counter

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ABSOLUTE MAXIMUM RATINGS
Exposure to conditions exceeding these ratings may cause damage!

Parameter	Min	Max	Units	Conditions
Supply Voltage, 3.3V to GND	+3.0	+3.6	V	
Analog Input Voltage, Vin to GND	-5.5	+5.5	V	
Operating Temperature	0	70	C	Non-condensing, forced air cooling required
Storage Temperature	-65	+150	C	
ESD Rating	-	1k	V	Human Body Model
Vibration	-	5	g	9-200 Hz, Class 3.3 per ETSI EN 300 019-1-3 V2.1.2 (2003-04)
Shock	-	40	g peak	Class 3.3 per ETSI EN 300 019-1-3 V2.1.2 (2003-04)

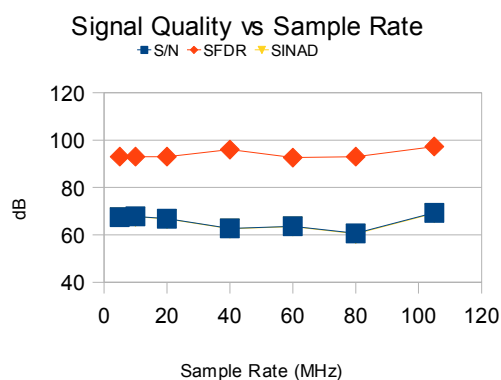**RECOMMENDED OPERATING CONDITIONS**

Parameter	Min	Typ	Max	Units
Supply Voltage	+3.15	+3.3	+3.45	V
A/D Sampling Rate	1		105	MSPS
DAC Update Rate	0		50	MSPS
Operating Temperature	0		60	C

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ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range at 0°C to +60°C, unless otherwise noted.

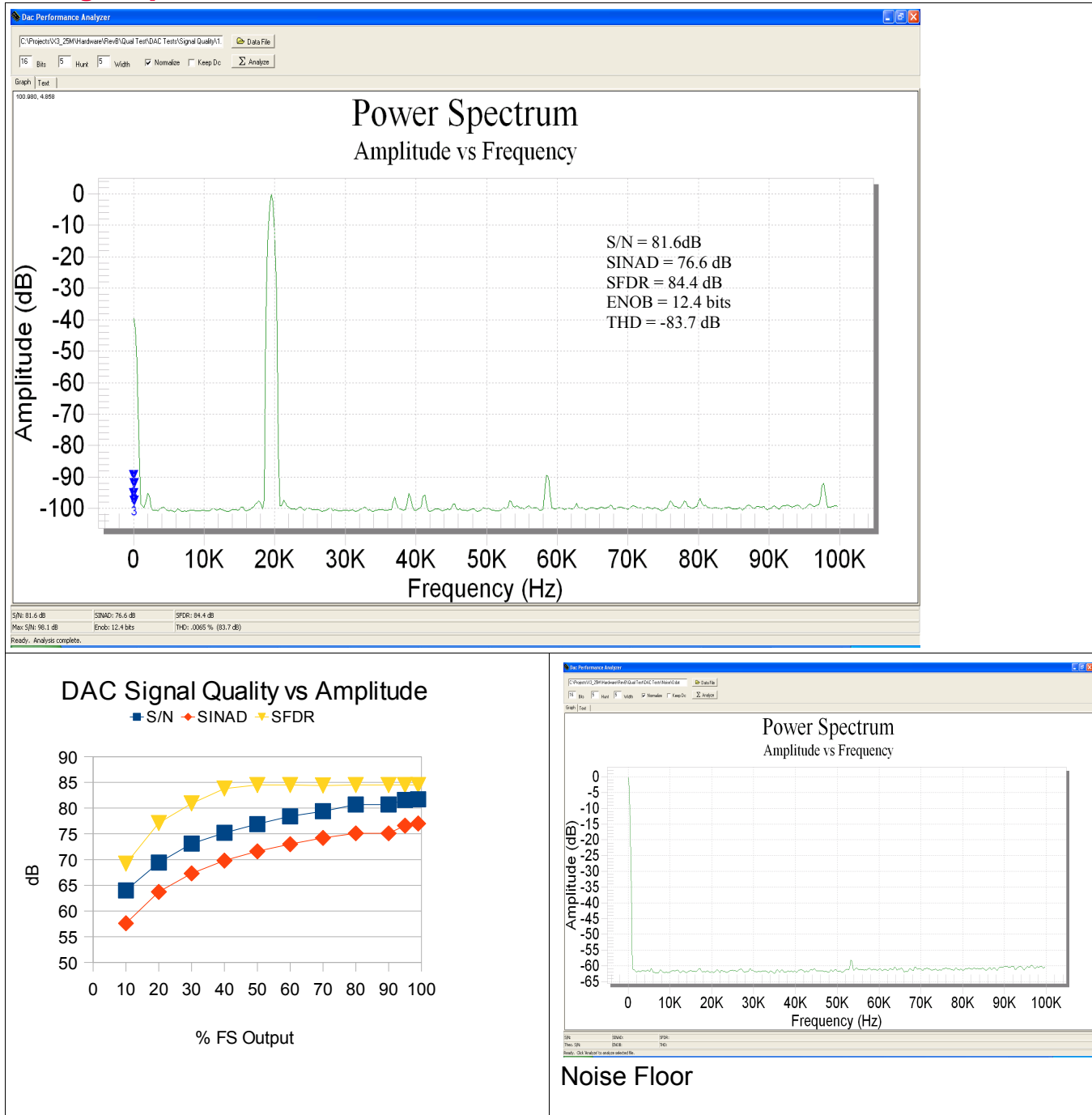| Group	Parameter	Typ	Units	Notes
Analog Inputs	Bandwidth	75	MHz	-3dB, typical
	SFDR	95	dB	10 kHz sine input, 2Vp-p, Fs= 105 MSPS
	S/N	69	dB	10 kHz sine input, 2Vp-p, Fs= 105 MSPS
	THD	-102	dB	10 kHz sine input, 2Vp-p, Fs= 105 MSPS
	ENOB	11.1	dB	10 kHz sine input, 2Vp-p, Fs= 105 MSPS
	Intermodulation Distortion	-93	dB	9 kHz and 11 kHz sines, 2Vp-p each; Fs = 105 MSPS
	Channel Crosstalk	<-100	dB	Input grounded with 4Vp-p input on other input; Fs= 105 MSPS
	Noise	8.6	µV p-p	Input grounded, FS=105 MSPS
	Gain Error	<0.005	% of FS	Calibrated
	Offset Error	<500	µV	Calibrated
Analog Outputs	Bandwidth	12.5	MHz	-3dB, typical
	SFDR	84.4	dB	20 kHz sine Output, 3.8Vp-p, Fs= 50 MSPS
	S/N	81.6	dB	20 kHz sine Output, 3.8Vp-p, Fs= 50 MSPS
	THD	-83.7	dB	20 kHz sine Output, 3.8Vp-p, Fs= 50 MSPS
	ENOB	12.4	dB	20 kHz sine Output, 3.8Vp-p, Fs= 50 MSPS
	Channel Crosstalk	<-95	dB	Other channel driven with 2Vp-p square wave; Fs= 50 MSPS
	Noise	-95	dB	Constant output, FS=50 MSPS
	Gain Error	<0.005	% of FS	Calibrated
	Offset Error	<500	µV	Calibrated
Power	Power Consumption	3.4	A	3.3V supply, all channels sampling at 105 MSPS, 27C
	Dissipation	11.2	W	3.3V supply, all channels sampling at 105 MSPS, 27C
	Calibration Interval	1	year	

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Analog Input Performance Data

Magnitude vs Frequency

SFDR=95.8 dB
ENOB = 11.2 bits
THD = -104.2 dB
S/N = 69.1dB
Fin = Sine at 10kHz, 2Vp-p
Fs = 105 MSPS, decimation = 10

Magnitude vs Frequency

Fin= 5 MHz

Signal Quality vs Sample Rate

Signal Quality vs Input Amplitude

Magnitude vs Frequency

Noise Floor

Amplitude vs Frequency
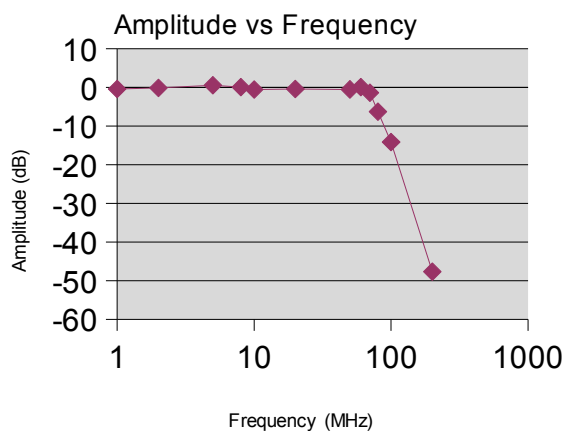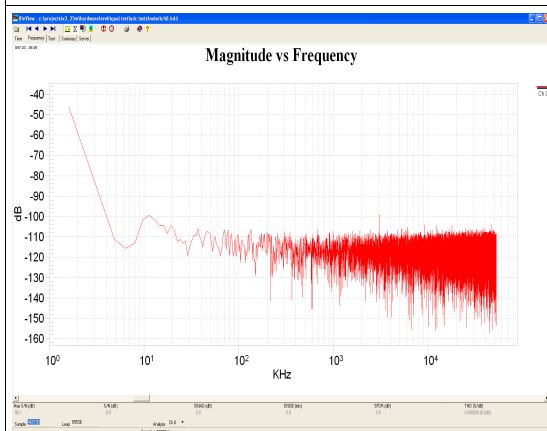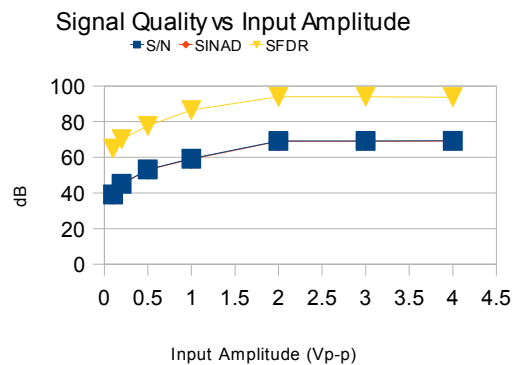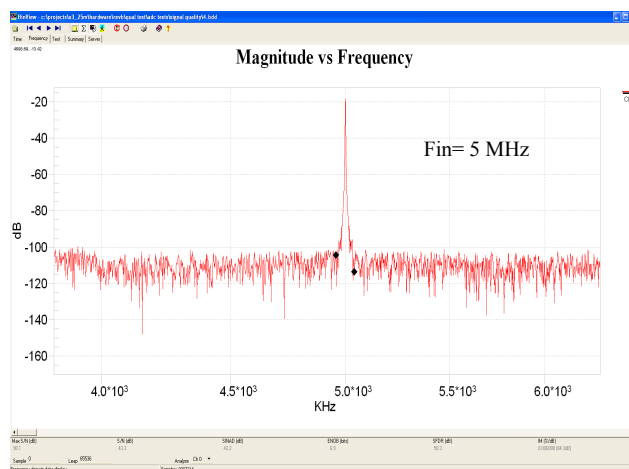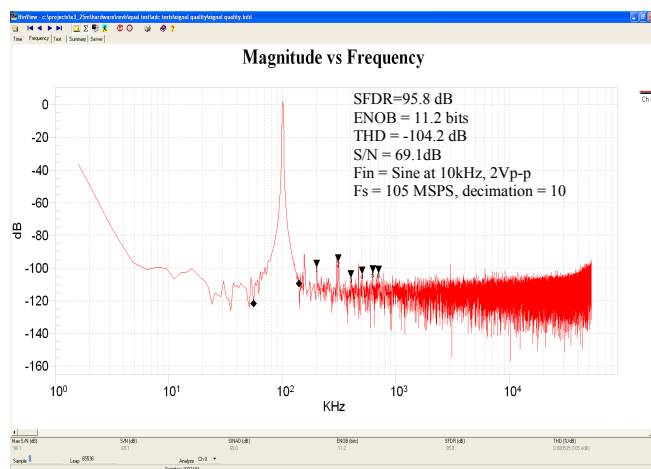
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Analog Output Performance Data

Power Spectrum
Amplitude vs Frequency

S/N = 81.6dB
SINAD = 76.6 dB
SFDR = 84.4 dB
ENOB = 12.4 bits
THD = -83.7 dB

DAC Signal Quality vs Amplitude
■ S/N ◆ SINAD ▼ SFDR

Power Spectrum
Amplitude vs Frequency

Noise Floor

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Architecture and Features

The X3-25M module has two analog input that are simultaneously sampling channels of 16-bit, 105 MSPS A/D input and two analog output channels of 50 MSPS, 16-bit D/A converter. The A/D inputs have programmable input ranges and an input bandwidth of 75 MHz. The two DAC channels have a +/-2V output range. Additional digital IO control bits from the FPGA are provided for application control and signaling.

Controls for triggering and clocks allow precise control over the collection of data. Trigger modes include frames of programmable size, external and software. Multiple X3-25M cards can sample simultaneously using external trigger inputs with synchronized sample clocks. The sample clock can be external or generated from the on-card PLL. The PLL can either use the on-card 100 MHz reference, or can use an external reference. When an external reference is used, the sample clock is synchronous to the reference.

The X3 architecture has a data buffering and packet system that provides efficient and flexible data transfers to the host computer. The data buffer is a 1M sample SRAM that is used as a dual-queue FIFO, one queue for A/D and one queue for DACs.. Data is transferred to the host using the PCIe controller interface as data packets. The packet data system controls the flow of packets to the host, or other recipient, using a credit-based system managed in cooperation with the host software. The packets may be transmitted continuously for streams of data from the A/Ds or DACs, or as occasional packets for status, controls and analysis results. The data buffering and flow control system delivers high throughput with low latency and complete flexibility for data types and packet sizes to match the application requirements for all types of applications.

Data flows between the IO and the host using a packet system

X3-25M Architecture

The data acquisition process can be monitored using the X3 alert mechanism. The alerts provide information on the timing of important events such as triggering, overranges and thermal overload. Packets containing data about the alert including an absolute system timestamp of the alert, and other information such as current temperature. This provides a precise overview of the card data acquisition process by recording the occurrence of these real-time events making the X3 modules easier to integrate into larger systems.

Software Tools

Software for data logging and analysis are provided with every X3 module. Data can be logged to system memory at full rate or to disk at rates supported by the drive and controller. Triggering, sample rate controls, and data logging features allow you to use X3 modules in your application without ever writing code. Innovative software applications include *Binview* which provides data viewing, analysis and export data to MATLAB for large data files, as well as support applications for logic loading, firmware updates and system configuration.

Software development tools for the X3 modules provide comprehensive support including device drivers, data buffering, card controls, and utilities that allow developers to be productive from the start. At the most fundamental level, the software tools deliver data buffers to your application without the burden of low-level real-time control of the cards. Software classes provide C++ developers a powerful, high-level interface to the card that makes real-time, high speed data acquisition easier to integrate into applications.
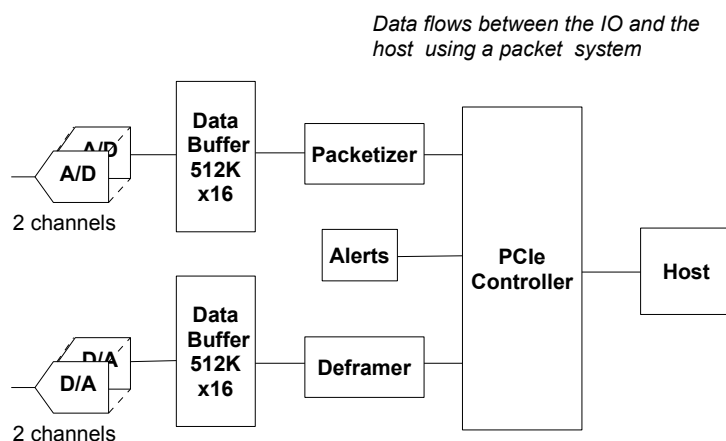
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Support for MS Visual C++ is provided. Supported OS include Windows and Linux. For more information, the software tools and on-line help may be downloaded.

Logic Tools

High speed DSP, analysis, customized triggering and other unique features may be added to the X3 modules by modifying the logic. The FrameWork Logic tools support RTL and MATLAB developments. The standard logic provides a hardware interface layer that allows designers to concentrate on the application-specific portions of the design. Designer can build upon the Innovative components for packet handling, hardware interfaces and system functions, the Xilinx IP core library, and third party IP. RTL source for the FrameWork Logic is provided for customization. Each design is provided as a Xilinx ISE project, with a ModelSim testbench illustrating logic functionality.
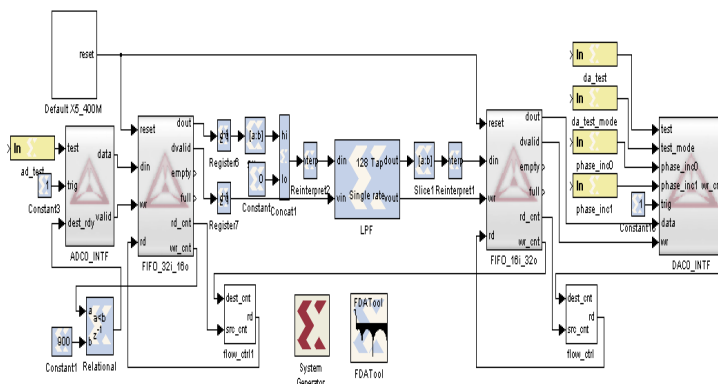
The MATLAB Board Support Package (BSP) supports logic development using Simulink and Xilinx System Generator. These tools provide a graphical design environment that integrates the logic into MATLAB Simulink for complete hardware-in-the-loop testing and development. The MATLAB tools are an extremely powerful design methodology that can be used to generate, analyze and display the signals in the logic real-time in the system. Once the development is complete, the logic can be embedded in the FrameWork logic using the Xilinx ISE tools.

The FrameWork Logic User sales brochure and User Guide more fully detail the development tools.

Applications Information

Maximum Data Rates

The maximum data rates supported by the module are limited by the PCI Express transfer rate when the total data rate exceeds 150 MB/s. The PCI Express transfer rate may vary according to the host computer, operating system, and other system activity that may compete for bandwidth. The X3 modules support 250MB/s full duplex during bursts, but actual sustained throughput is 150 MB/s in typical desktop PCs.

It is important to qualify systems for performance when data rates exceeding 150 MB/s are required.

This rate limitation does not apply to data generated in the FPGA.

Cables

X3 modules uses a shielded, jacketed 68-wire cable assembly for the front panel IO. The pleated copper foil shield cable is "near coax" in its performance. This cable, plus the use of differential signals and use of ground signals as shields, produce the best results. A screw terminal assembly is available.
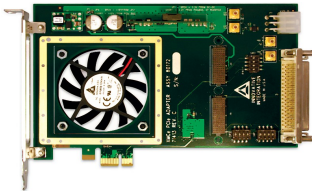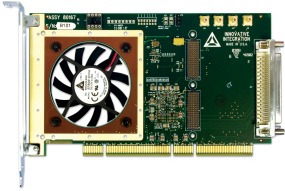

XMC Adapter Cards

XMC modules can be used in standard desktop system or compact PCI/PXI using an adapter card. The adapter cards are software transparent.

The X3 modules use the auxiliary P16 connector for digital IO and additional clock inputs. A total of 44 bits of digital IO, directly connected to the application FPGA, are routed to the rear edge MDR connector as 22 balanced differential pairs

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supporting LVDS or lower speed single-ended LVCMOS signals. The X3 modules also have a sample clock input and PLL reference input to J16. The cPCI/PXI adapter uses these to connect to system clocks, while the PCIe desktop adapter provides SMB input connectors for system clock inputs.

PCIe-XMC Adapter (80172)	**PCI-XMC Adapter (80167)**	**Compact PCI-XMC Adapter (80207)**
x1 PCIe to XMC	64-bit, 133 MHz PCI-X host	64-bit, 133 MHz PCI-X host
SMB Clock and trigger inputs	x4 PCIe to XMC	x4 PCIe to XMC
		PXI triggers and clock support

Applications that need remote or portable IO can use either the eInstrument PC or eInstrument Node with X3 modules.

eInstrument PC with Dual PCI Express XMC Modules (90199)	**eInstrument DAQ Node – Remote IO using cabled PCI Express (90181)**
Windows/Linux embedded PC	PCI Express system expansion
8x USB, GbE, cable PCIe, VGA	Up to 7 meter cable
High speed x8 interconnect between modules	electrically isolated from host computer
GPS disciplined, programmable sample clocks and triggers to XMCs	software transparent
Up to 400MB/s data logging using FLASH HDD	
12V operation	

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